■ MN101C38A , MN101C38C

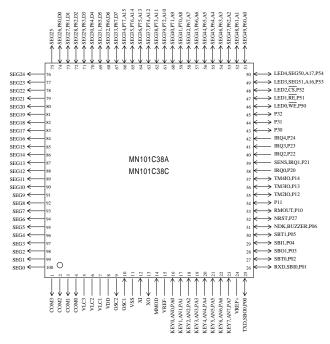
Туре			MN101C38A	MN101C38C			
ROM (×8-bit)			32 K	48 K			
External memory can be expanded							
RAM (×8-bit)			1.5 K	2 K			
External memory can be expanded							
Package	Package		QFP100-P-1818B *Lead-free, LQFP100-P-1414 *Lead-free				
Minimum Instruction Execution Time Interrupts		0.1 µs (at 4.5 V to 5.5 V, 20 MHz)					
		0.25 μs (at 2.7 V to 5.5 V, 8 MHz)					
		125 μs (at 2.0 V to 5.5 V, 32 kHz)* * The lower limit for exercise guerantee for EDROM built in type is 2.3 V					
		* The lower limit for operation guarantee for EPROM built-in type is 2.3 V.					
		• RESET • Watchdog • External 0 • External 1 • External 2 • External 3 • External 4 • Timer 2 • Timer 3 • Timer 4 • Timer 5 • Time base • Serial 0 • Serial 1 • A/D conversion finish					
Timer Count	Timor Counter		Timer counter 2 : 8-bit × 1 (square-wave/8-bit PWM output, event count, synchronous output event)				
Timer Counter		Clock source					
		external clock input					
		Interrupt source ······ coincidence with compare register 2					
		Timer counter $3: 8$ -bit $\times 1$					
		(square-wave output, event count, generation of remote control carrier, serial 0 baud rate timer)					
		Clock source					
		Interrupt source coincidence with compare register 3					
		Timer counter 2, 3 can be cascade-connected.					
			Timer counter 4 : 16-bit × 1				
		(square-wave/16-bit PWM output, event count, synchronous output event, input capture)					
		Clock source					
		Interrupt source coincidence with compare register 4					
		Time base timer (one-minute count setting, independently operable 8-bit timer counter 5)					
		Clock source 1/4 of system clock frequency; 1/1, 1/8192 of OSC oscillation clock frequency					
		1/1, 1/8192 of XI oscillation clock frequency Interrupt sourcecoincidence with compare register 5; 1/8192 prescaler overflow					
		Watchdog timer Interrupt source					
Serial Interfa	Sorial Interface		Serial 0 : synchronous type/simple UART (half-duplex) × 1				
Serial interface		Clock source					
		Serial 1 : synchronous type × 1					
		5011		stem clock frequency; 1/2 of timer counter 3 frequency			
I/O Pins	I/O	44	• Common use • Specified pull-up resistor available • Input/output selectable (bit unit) • Specified pull-down resistor partially selectable				
	Input	13	Common use • Specified pull-up resistor ava	ilable • Specified pull-down resistor partially selectable			
A/D Inputs		10 -bit \times 8-ch. (with S/H)					
LCD		52 segments × 4 commons (Static, 1/2, 1/3, or 1/4 duty)					
Special Ports	Chasial Dayto		Buzzer output, remote control carrier signal output, high-current drive port				

Electrical Characteristics

Supply current

Parameter	Symbol	Condition		Limit		
raidilletei	Symbol			typ	max	Unit
Operating cumply ourrent	IDD1	fosc = 8 MHz, VDD = 5 V		10	25	mA
Operating supply current	IDD2	fx = 32 kHz, VDD = 3 V		30	100	μА
Supply current at HALT	IDD3	$fx = 32 \text{ kHz}, VDD = 3 \text{ V}, Ta = 25^{\circ}\text{C}$			8	μА
Supply current at HALI	IDD4	$fx = 32 \text{ kHz}, VDD = 3 \text{ V}, Ta = -40^{\circ}\text{C to } +85^{\circ}\text{C}$			24	μА
Supply current at STOP	IDD5	$VDD = 5 \text{ V}, \text{ Ta} = 25^{\circ}\text{C}$			1	μА
Supply cultent at STOP	נעעוו	$VDD = 5 \text{ V}, \text{ Ta} = -40^{\circ}\text{C to} +85^{\circ}\text{C}$			20	μА

Pin Assignment



QFP100-P-1818B *Lead-free LQFP100-P-1414 *Lead-free

Support Tool

In-circuit Emulator	PX-ICE101C / D + PX-PRB101C38-QFP100-P-1818B PX-ICE101C / D + PX-PRB101C38-LQFP100-P-1414					
EPROM Built-in Type	Туре	MN101CP38C				
	ROM (× 8-bit)	48 K				
	RAM (× 8-bit)	2 K				
	Minimum instruction execution time	0.1 μs (at 4.5 V to 5.5 V, 20 MHz)				
		$0.25~\mu s$ (at 2.7 V to 5.5 V, 8 MHz)				
		$125~\mu s$ (at $2.3~V$ to $5.5~V,32~kHz)$				
	Package	QFP100-P-1818B *Lead-free, LQFP100-P-1414 *Lead-free				

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